CLAIMS

1. System including a wafer (3) and an accommodating device for accommodation and mounting of a wafer (3) for application of fluid (9) to a top (3o) of the wafer (3) with the following features:
   - a revolving ring section (4) with:
     a) a revolving upper edge (5),
     b) a revolving recess (6), and
     c) a circumferential wall (7) running from the upper edge (5) to the recess (6),
   - a contact plane (A) arranged within the ring section (4) for the accommodation of the wafer (3) on a contact surface (3a) of the wafer (3),

   wherein the ring section (4) by means of accommodation of the wafer (3) forms with said wafer an accommodating space (8) for accommodation of the fluid (9), wherein a sealing takes place at a circumferential edge (3k) of the wafer (3).

2. System according to claim 1, characterized in that the circumferential wall (7) is contoured in accordance with a circumferential edge (3k) of the wafer (3).

3. System according to claim 1, characterized in that it exhibits an overflow plane (C) differing from the contact plane (A) formed by the upper edge (5), in particular running parallel to the contact plane (A).

4. System according to claim 3, characterized in that the distance (D) between the contact plane (A) and the overflow plane (C) is greater than the thickness d of the wafer (3) to be accommodated.

5. System according claim 1, characterized in that it exhibits an accommodation opening (10) formed by the upper edge (5) and the circumferential wall (7) for the accommodation of the wafer (3).

6. System according to claim 1, characterized in that it exhibits a mounting surface (2) formed at least partially by
   - the circumferential wall (7) and/or
   - the recess (6) or
   - at least one accommodating projection (11) provided on the recess (6).

7. System according to claim 6, characterized in that the mounting surface (2) is constructed as less than 50% of the contact surface (3a), in particular less than 25% of the contact surface (3a), preferably less than 10% of the contact surface (3a).

8. System according to claim 1, characterized in that the ring section (4) is constructed circumferentially enclosed.

9. System according to claim 1, characterized in that contact elements (12) are provided joining to the recess (6), in particular provided in the form of a brace, preferably converging in a center of the accommodating device (1) converging.

10. System according to claim 1, characterized in that at least one projection (13) is provided on the circumferential wall (7) for fixation of the wafer (3) in a rotational direction (R).

11. Method for accommodation and mounting of a wafer (3) for application of fluid (9) to a top (3o) of the wafer (3) with the following features:
   - providing a revolving ring section (4) with:
     a) a revolving upper edge (5),
     b) a revolving recess (6), and
     c) a circumferential wall (7) running from the upper edge (5) to the recess (6),

- accommodation of a contact surface (3a) of the wafer (3) on a contact plane (A) arranged within the ring section (4), wherein the ring section (4) by means of accommodation of the wafer (3) forms with said wafer an accommodating space (8) for accommodation of the fluid (9), and wherein a sealing takes place at a circumferential edge (3k) of the wafer (3).